CHANGE NOTIFICATION

Linear Technology Corporation
1630 McCarthy Blvd., Milpitas, CA
95035-7417
(408) 432-1900

December 19, 2012 PCN#: 121912

Dear Sir/Madam:

Subject: **Notification of Assembly Process change for LTM8022, LTM8023 and LTM8052**

Please be advised that Linear Technology Corporation has made a minor change to the internal package construction to facilitate the use of one attach material for both die and components. The die attach material is changed from epoxy to solder, which is already used for attaching components in the same µModule device package. In order to use the solder die attach, the die paddle (DAP) has been modified by splitting the DAP into multiple pads for dice D1, Q1 and U1. Linear has been shipping several µModule devices using solder for die attach and component attach.

Besides these changes, no functional, parametric, mechanical, or datasheet specifications are affected and the component bill of materials remains unchanged. Similarly, there are no changes associated with the package footprint, PCB layout or product top marking, so customer applications will be unaffected.

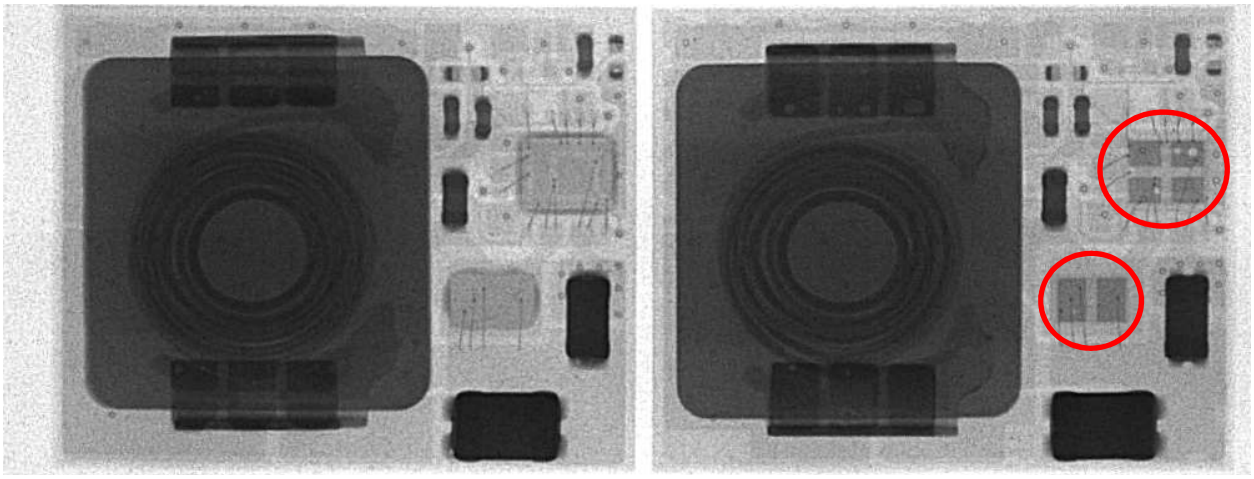
Parts incorporating the new substrate design have been fully characterized and tested for package level reliability. The change was qualified by performing extensive characterization over the full operating voltage and temperature ranges and MSL3 preconditioning. Devices from the same µModule device product families have been subjected to 1000 cycles of temperature cycles and thermal shock. Products built using the improved design are targeted for shipment around late February 2013.

Should you have any further questions, please feel free to contact me at 408-432-1900 ext. 2519, or by E-mail at NGIRN@linear.com. If I do not hear from you by January 21st, 2013, we will consider this change approved by your company.

Sincerely,

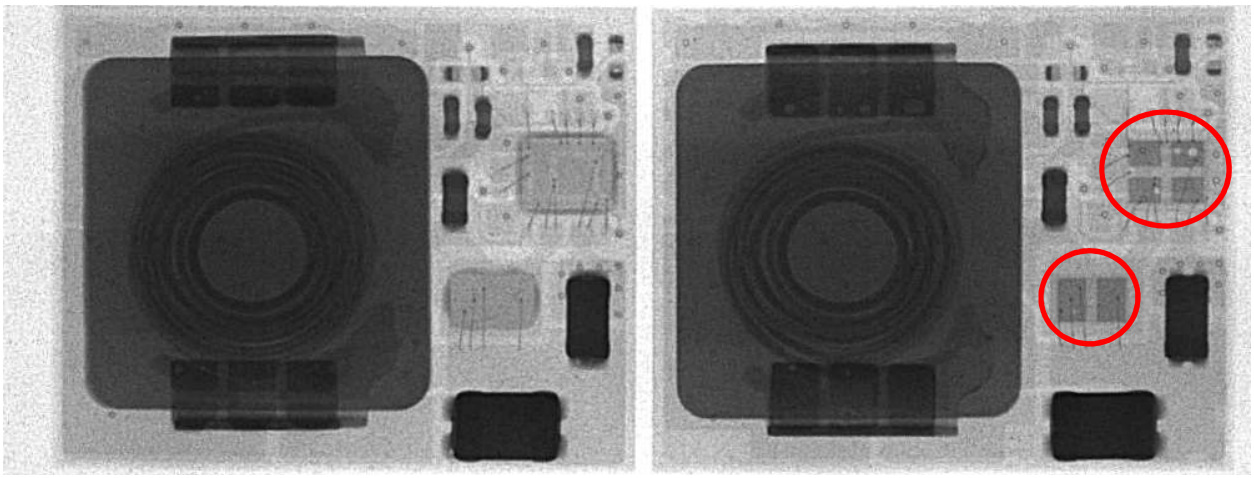
Naib Girn
Quality Assurance Manager

LTM8022- Current and New DESIGN



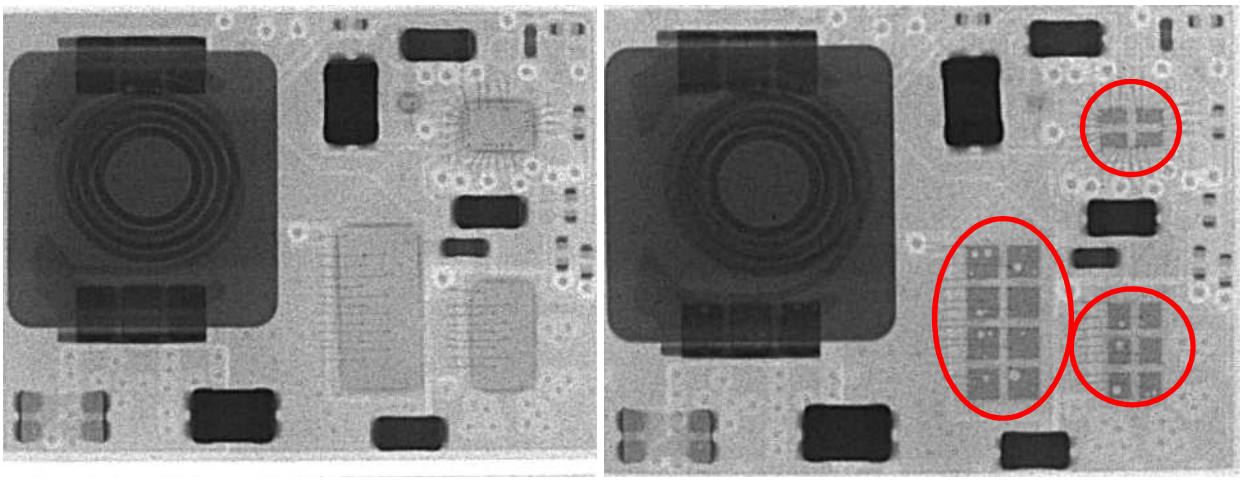
Current Design **New Design**

LTM8023 Current and New Design



Current Design **New Design**

LTM8052 Current and New Design



Current Design **New Design**

PACKAGE RELIABILITY DATA
LTM80xx Solder Die Attach Qualification Report
12/11/2012

• OPERATING LIFE TEST

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +150°C	NUMBER OF FAILURES
LTM8008	77	1210	1210	77.00	0
	77			77.00	0

• J-STD-020 MSL 3 PRECONDITIONING: 192h +30°C/60%R.H. SOAK, 3x REFLOW AT +245°C PEAK

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE		NUMBER OF FAILURES
LTM8001	199	1236	1236		0
LTM8008	462	1210	1210		0
LTM8023	204	1245	1245		0
LTM8028	184	1236	1236		0
LTM8045	152	1225	1225		0
LTM8048	274	1232	1236		0
LTM8052	204	1239	1239		0
	1,679				0

• HIGH TEMPERATURE BAKE at 150°C

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +150°C	NUMBER OF FAILURES
LTM8008	77	1210	1210	77.00	0
LTM8045	50	1225	1225	50.00	0
	127			127.00	0

• HIGHLY ACCELERATED STRESS TEST (+131°C/85%R.H. w BIAS)

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +85°C	NUMBER OF FAILURES
LTM8008	46	1210	1210	88.32	0
	46			88.32	0

• TEMPERATURE/HUMIDITY STORAGE (+85°C/85%R.H.) (1)

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +85°C	NUMBER OF FAILURES
LTM8001	25	1236	1236	12.50	0
LTM8008	77	1210	1210	77.00	0
	77			77.00	0

PACKAGE RELIABILITY DATA
LTM80xx Solder Die Attach Qualification Report
12/11/2012

• TEMP CYCLE FROM -65°C to +150°C [1]

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
LTM8008	231	1210	1210	231.00	0
	231			231.00	0

• TEMP CYCLE FROM -55°C to +125°C [1]

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
LTM8045	77	1225	1225	77.00	0
LTM8048	102	1232	1236	140.50	0
	179			217.50	0

• THERMAL SHOCK FROM -65°C to +150°C [1]

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
LTM8008	231	1210	1210	231.00	0
	231			231.00	0

• THERMAL SHOCK FROM -55°C to +125°C [1]

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
LTM8045	75	1225	1225	75.00	0
LTM8048	126	1232	1236	87.50	0
	201			162.50	0

• BOARD MOUNT TEMP CYCLE FROM -40°C to +125°C

DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
LTM8008	15	1210	1210	22.50	0
	15			22.50	0

(1) Environmental stress are preceded by JEDEC Level 3 Preconditioning: 192h 30°C/60% R.H. soak, followed by 3x Reflow at 245°C